

G2L5-DR4-L08

HPC/AI Server - 2U DP NVIDIA HGX™ Rubin NVL8 DLC



Key Features

- Liquid-cooled NVIDIA HGX™ Rubin NVL8
- CPU+GPU direct liquid cooling solution with leak detection
- 8 x 800 Gb/s OSFP InfiniBand or Ethernet GPU networking ports via 8 x single-port NVIDIA ConnectX®-9 VPI
- 3.6 TB/s GPU-to-GPU bandwidth with NVIDIA NVLink™
- Dual AMD EPYC™ 9006 SP7 Server processors
- 16-Channel DDR5 RDIMM/MRDIMM per CPU with 32 x DIMMs [\[DLC\]](#)
- 1 x 1 Gb/s LAN ports via Intel® I210-AT
- 2 x M.2 slots with PCIe Gen4 x4
- 8 x E1.S Gen6 NVMe hot-swap bays [\[DLC\]](#)
- 1 x FHFL PCIe x16 (Gen6 x16) for NVIDIA BlueField®-4 DPU [\[DLC\]](#)
- 54 V DC Bus Bar power solution

Applications

AI Platform, AI Training Server, AI Inference Server, High-Performance Computing Server...

Specification

Dimensions	2U (W449.6 x H87 x D808 mm)	Modular GPU	[DLC] NVIDIA HGX™ Rubin NVL8
Motherboard	MDB5-MG0	PCIe Expansion Slots	[DLC] 1 x FHFL x16 (Gen6 x16), for NVIDIA BlueField®-4 DPU
CPU	AMD EPYC™ 9006 SP7 Server processors [DLC] Dual processors, PPT up to 600 W	I/O Ports	Front: 8 x OSFP, 2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN
Socket	2 x LGA 7536 (Socket SP7)	TPM	1 x TPM header (SPI), Optional TPM 2.0 kit: CTM012
Chipset	Integrated into SoC	Power Supply	1 x 54 V DC Bus Bar Connector
Memory	16-Channel DDR5 RDIMM/MRDIMM, 32 x DIMMs [RDIMM] Up to 8000 MT/s [MRDIMM] Up to 12800 MT/s ^[1] ^[1] MRDIMMs are supported only on select CPU SKUs.	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing) *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
LAN	[DLC] 8 x 800 Gb/s OSFP InfiniBand or Ethernet, for GPU networking, via NVIDIA ConnectX®-9 VPI 1 x 1 Gb/s LAN (1 x Intel® I210-AT), Support NCSI 1 x Management LAN	Packaging Content	1 x G2L5-DR4-L08 1 x Rail kit
Video	Integrated in ASPEED® AST2700 - 1 x Mini-DP	Ordering Part Numbers	6NG2L5DR4DR000L08*
Storage	Front hot-swap: [DLC] 8 x E1.S Gen6 NVMe, from CX-9 Internal M.2: 2 x M.2 (2280), PCIe Gen4 x4		



Learn more at: <https://www.gigabyte.com/Enterprise>

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